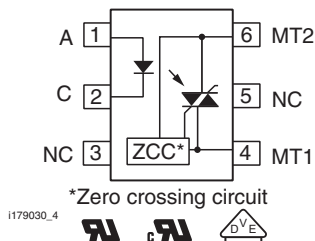
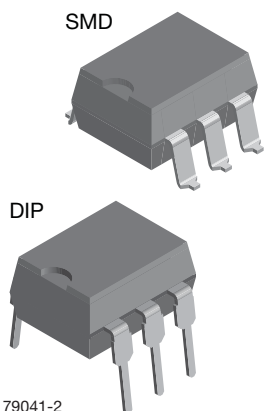


Optocoupler, Phototriac Output, Zero Crossing, 1.5 kV/μs dV/dt, 600 V



FEATURES

- 1500 V/μs dV/dt minimum
- 600 V blocking voltage
- 100 mA on-state current
- Zero crossing detector
- Low input trigger current
- 6 pin DIP package
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS COMPLIANT

APPLICATIONS

- Household appliances
- Triac drive / AC motor drives
- Solenoid / valve controls
- Office automation equipment / machine
- Temperature (HVAC) / lighting controls
- Switching power supply

AGENCY APPROVALS

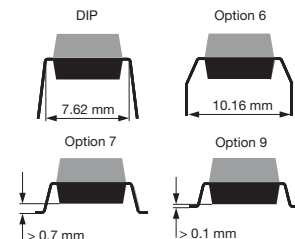
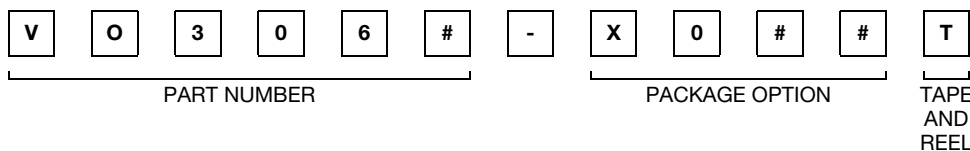
- UL1577, file no. E52744
- cUL - file no. E52744, equivalent to CSA bulletin 5A
- DIN EN 60747-5-5 (VDE 0884-5) available with option 1

DESCRIPTION

The VO3062 and VO3063 triac driver family consists of a GaAs infrared LED optically coupled to a monolithic photosensitive zero crossing triac detector chip.

The 600 V blocking voltage permits control of off-line voltages up to 240 V_{AC}, with a safety factor of more than two, and is sufficient for as much as 380 V.

ORDERING INFORMATION



AGENCY CERTIFIED/PACKAGE	TRIGGER, CURRENT I _{FT} (mA)	
	5	10
UL, cUL		
DIP-6	VO3063	VO3062
DIP-6, 400 mil, option 6	VO3063-X006	VO3062-X006
SMD-6, option 7	VO3063-X007T	VO3062-X007T
SMD-6, option 9	VO3063-X009T	-
VDE, UL, cUL		
	5	10
DIP-6, 400 mil, option 6	VO3063-X016	VO3062-X016
SMD-6, option 7	VO3063-X017T	VO3062-X017T

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)					
PARAMETER	TEST CONDITION	PART	SYMBOL	VALUE	UNIT
INPUT					
Reverse voltage			V_R	6	V
Forward current - continuous			I_F	60	mA
Power dissipation			P_{diss}	100	mW
OUTPUT					
Off state output terminal voltage		VO3062, VO3063	V_{DRM}	600	V
Peak non-repetitive surge current	PW = 100 μ s, 120 pps		I_{TSM}	1	A
Power dissipation			P_{diss}	200	mW
On-state RMS current			$I_{T(RMS)}$	100	mA
COUPLER					
Total power dissipation			P_{tot}	300	mW
Operating temperature range			T_{amb}	-55 to +100	$^{\circ}\text{C}$
Storage temperature range			T_{stg}	-55 to +150	$^{\circ}\text{C}$
Soldering temperature ⁽¹⁾	Maximum \leq 10 s		T_{slid}	260	$^{\circ}\text{C}$

Notes

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability
- ⁽¹⁾ Refer to reflow profile for soldering conditions for surface mounted devices (SMD). Refer to wave profile for soldering conditions for through hole devices (DIP) "Assembly Instructions" (www.vishay.com/doc?80054)

THERMAL CHARACTERISTICS				
PARAMETER	SYMBOL	VALUE	UNIT	
Maximum LED junction temperature	T_{jmax}	125	$^{\circ}\text{C}$	
Maximum output die junction temperature	T_{jmax}	125	$^{\circ}\text{C}$	
Thermal resistance, junction emitter to board	θ_{JEB}	150	$^{\circ}\text{C}/\text{W}$	
Thermal resistance, junction emitter to case	θ_{JEC}	139	$^{\circ}\text{C}/\text{W}$	
Thermal resistance, junction detector to board	θ_{JDB}	78	$^{\circ}\text{C}/\text{W}$	
Thermal resistance, junction detector to case	θ_{JDC}	103	$^{\circ}\text{C}/\text{W}$	
Thermal resistance, junction emitter to junction detector	θ_{JED}	496	$^{\circ}\text{C}/\text{W}$	
Thermal resistance, case to ambient	θ_{CA}	3563	$^{\circ}\text{C}/\text{W}$	

Note

- The thermal model is represented in the thermal network below. Each resistance value given in this model can be used to calculate the temperatures at each node for a given operating condition. The thermal resistance from board to ambient will be dependent on the type of PCB, layout and thickness of copper traces. For a detailed explanation of the thermal model, please reference Vishay's Thermal Characteristics of Optocouplers application note



ELECTRICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)							
PARAMETER	TEST CONDITION	PART	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT							
Reverse current	$V_R = 6\text{ V}$		I_R	-	-	10	μA
Forward voltage	$I_F = 30\text{ mA}$		V_F	-	1.2	1.5	V
OUTPUT							
Leakage with LED off, either direction	$V_{DRM} = 600\text{ V}$		I_{DRM}	-	10	500	nA
Critical rate of rise off-state voltage	$V_D = 400\text{ V}$		dV/dt	1500	2000	-	V/ μs
COUPLER							
LED trigger current, current required to latch output		VO3063	I_{FT}	-	-	5	mA
		VO3062	I_{FT}	-	-	10	mA
Peak on-state voltage, either direction	$I_{TM} = 100\text{ mA Peak}$, $I_F = \text{rated } I_{FT}$		V_{TM}	-	1.7	3	V
Holding current, either direction			I_H	-	200	-	μA
Inhibit voltage (MT1-MT2 voltage above which device will not trigger)			V_{INH}	-	12	22	V
Leakage in inhibited state	$I_F = 10\text{ mA maximum}$, at rated V_{DRM} , off state		V_{DRM2}	-	250	1000	μA

Note

- Typical values are characteristics of the device and are the result of engineering evaluations. Typical values are for information only and are not part of the testing requirements

SAFETY AND INSULATION RATINGS				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Climatic classification	According to IEC 68 part 1		55 / 100 / 21	
Pollution degree	According to DIN VDE 0109		2	
Comparative tracking index	Insulation group IIIa	CTI	175	
Maximum rated withstanding isolation voltage	According to UL1577, $t = 1\text{ min}$	V_{ISO}	4420	V_{RMS}
Tested withstanding isolation voltage	According to UL1577, $t = 1\text{ s}$	V_{ISO}	5300	V_{RMS}
Maximum transient isolation voltage	According to DIN EN 60747-5-5	V_{IOTM}	8000	V_{peak}
Maximum repetitive peak isolation voltage	According to DIN EN 60747-5-5	V_{IORM}	890	V_{peak}
Isolation resistance	$T_{amb} = 25\text{ }^{\circ}\text{C}$, $V_{IO} = 500\text{ V}$	R_{IO}	$\geq 10^{12}$	Ω
	$T_{amb} = 100\text{ }^{\circ}\text{C}$, $V_{IO} = 500\text{ V}$	R_{IO}	$\geq 10^{11}$	Ω
Output safety power		P_{SO}	400	mW
Input safety current		I_{SI}	150	mA
Input safety temperature		T_S	165	$^{\circ}\text{C}$
Creepage distance	DIP-6		≥ 7	mm
Clearance distance			≥ 7	mm
Creepage distance	DIP-6, 400 mil, option 6		≥ 8	mm
Clearance distance			≥ 8	mm
Creepage distance	SMD-6, option 7		≥ 7	mm
Clearance distance			≥ 7	mm
Creepage distance	SMD-6, option 9		≥ 8	mm
Clearance distance			≥ 8	mm
Insulation thickness		DTI	≥ 0.4	mm

Note

- As per IEC 60747-5-5, § 7.4.3.8.2, this optocoupler is suitable for “safe electrical insulation” only within the safety ratings. Compliance with the safety ratings shall be ensured by means of protective circuits

TYPICAL CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

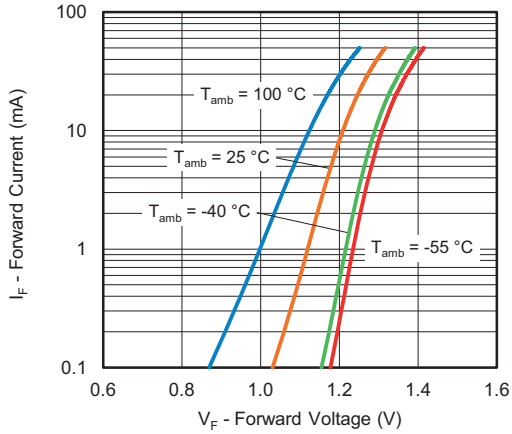


Fig. 1 - Forward Current vs. Forward Voltage

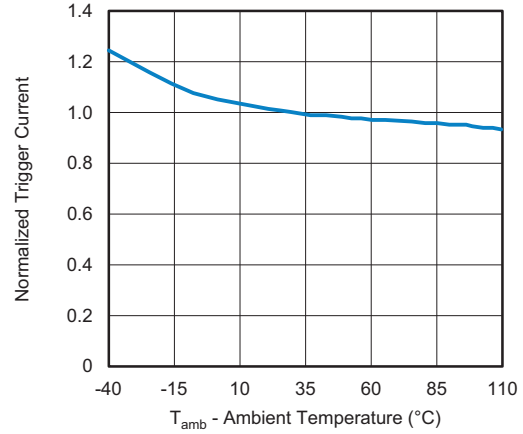


Fig. 4 - Normalized Trigger Current vs. Ambient Temperature

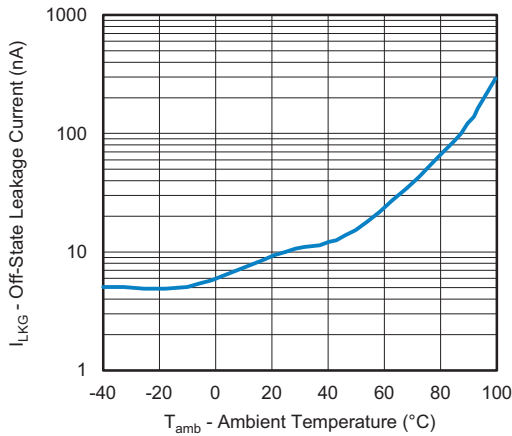


Fig. 2 - Off-State Leakage Current vs. Ambient Temperature

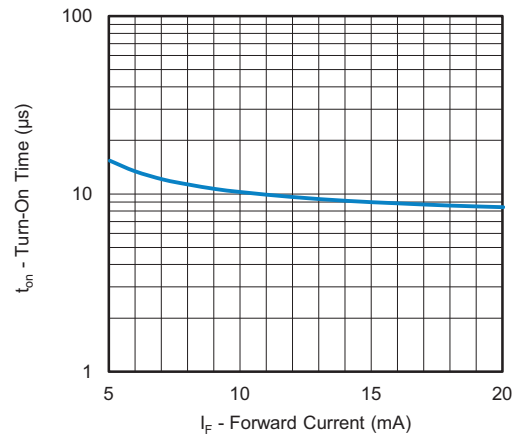


Fig. 5 - Turn-on Time vs. Forward Current

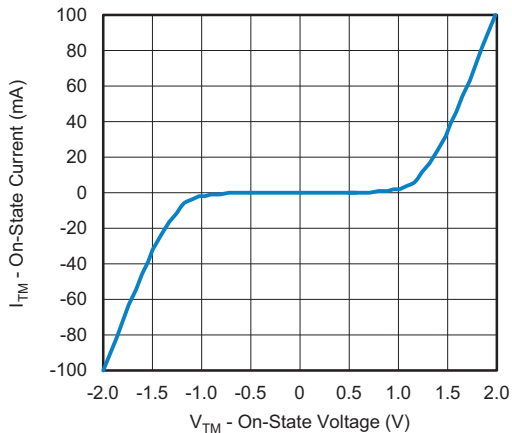


Fig. 3 - On-State Current vs. On-State Voltage

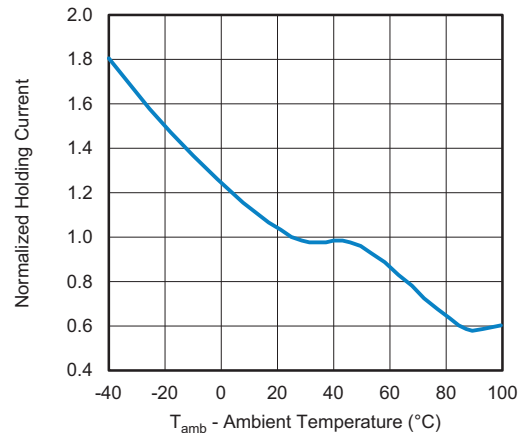


Fig. 6 - Normalized Holding Current vs. Ambient Temperature

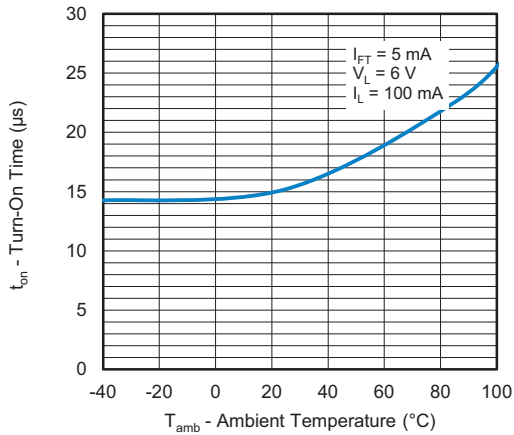


Fig. 7 - Turn-on Time vs. Ambient Temperature

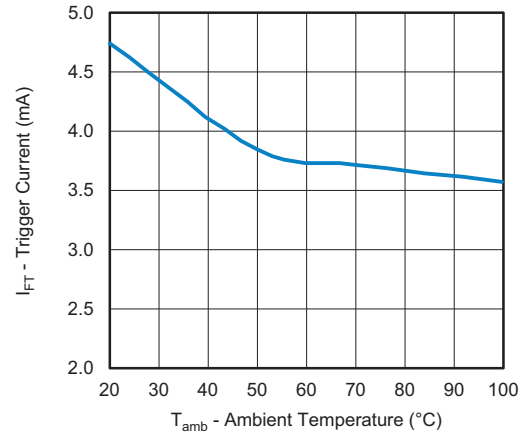
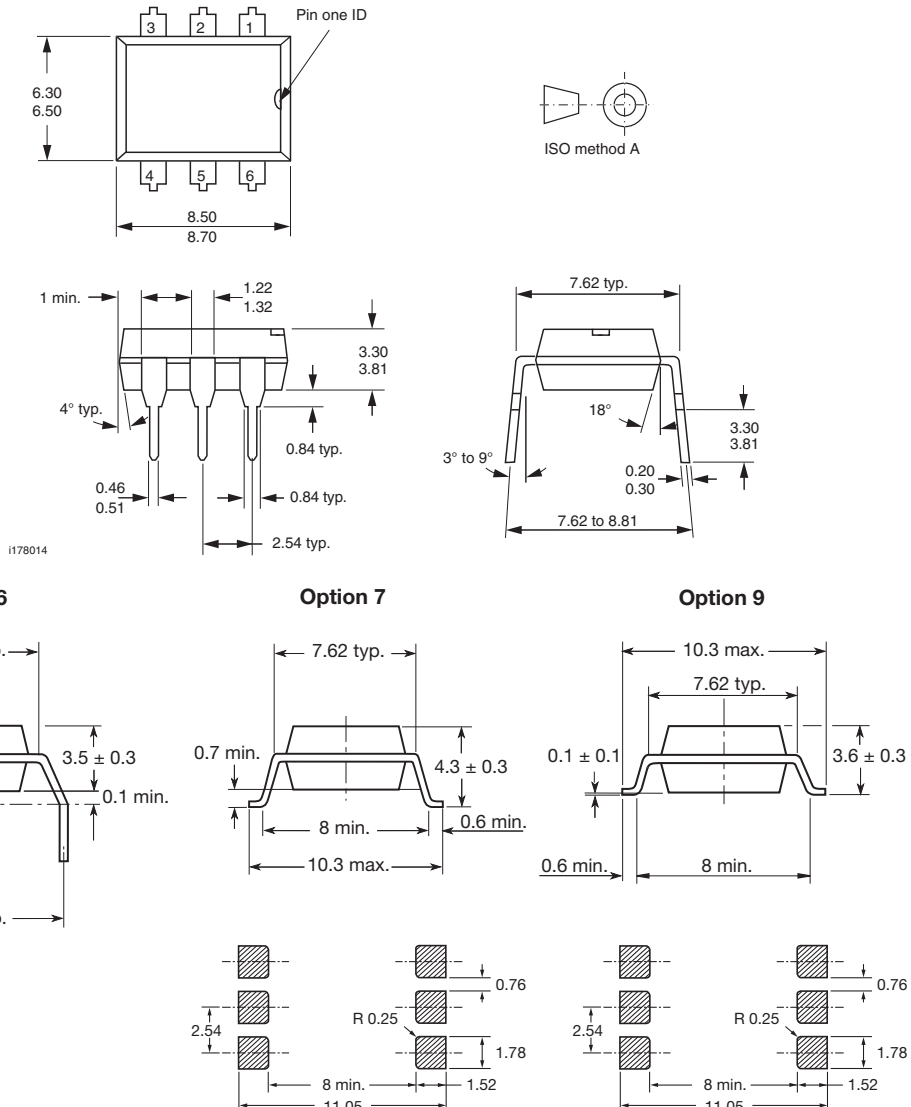
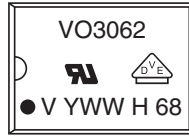


Fig. 8 - Trigger Current vs. Pulse Width

PACKAGE DIMENSIONS (in millimeters)



PACKAGE MARKING (example of VO3062-X016)



Notes

- The VDE logo is only marked on option1 parts.
- Tape and reel suffix (T) is not part of the package marking.

PACKING INFORMATION (in millimeters)

Tube

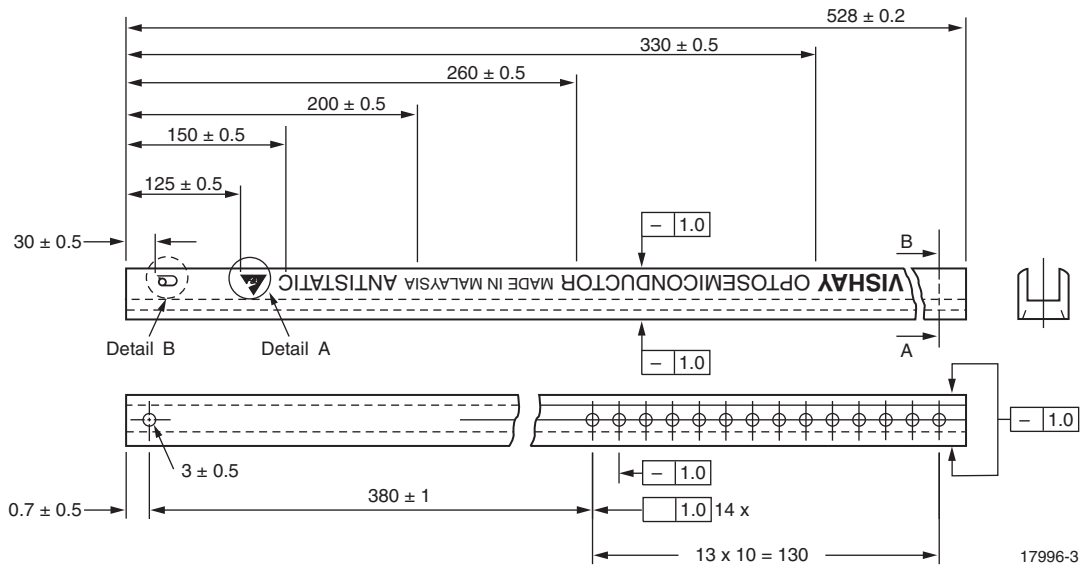


Fig. 9 - Shipping Tube Specifications for DIP Packages

DEVICES PER TUBS			
TYPE	UNITS/TUBE	TUBES/BOX	UNITS/BOX
DIP-6	50	40	2000

DIP-6

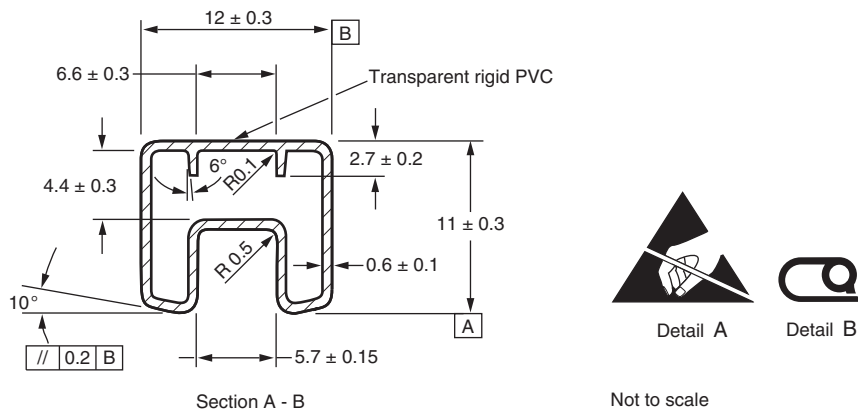


Fig. 10 - Tube Shipping Medium

DIP-6, 400 mil, option 6

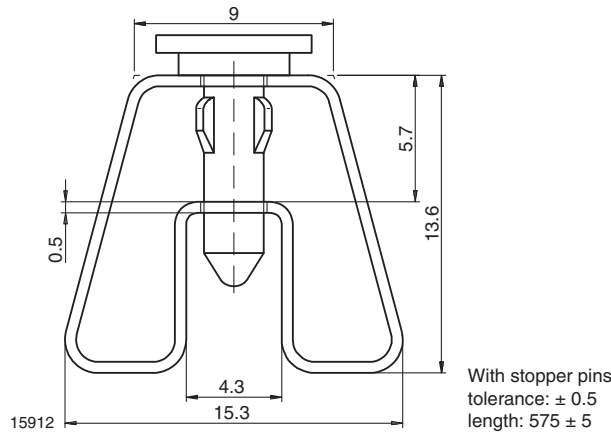


Fig. 11 - Tube Shipping Medium

Tape and Reel

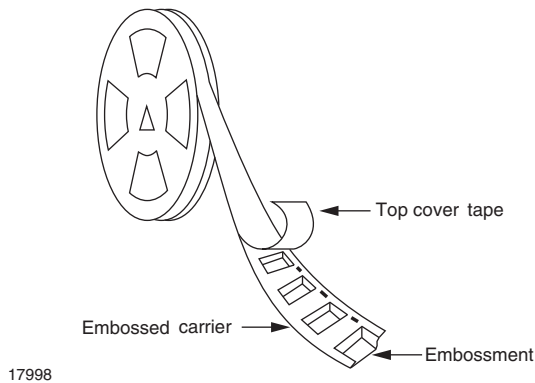


Fig. 12 - Tape and Reel Shipping Medium

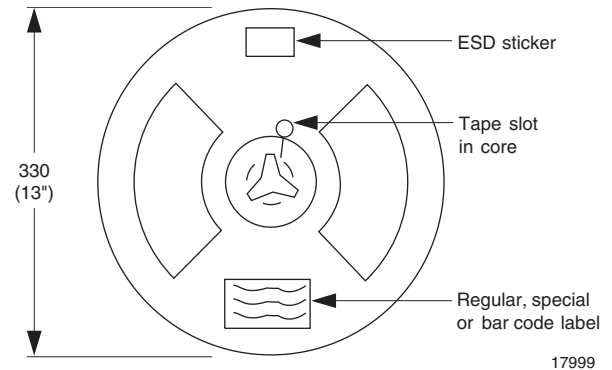


Fig. 13 - Tape and Reel Shipping Medium

SMD-6, option 7

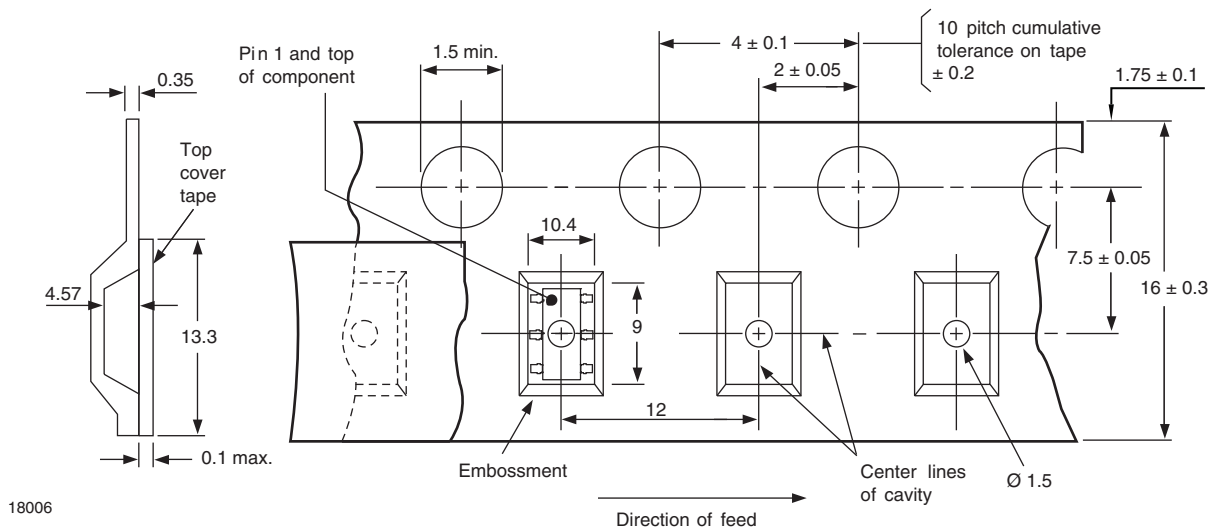


Fig. 14 - Tape and Reel Packing (1000 pieces on Reel)

SMD-6, option 9

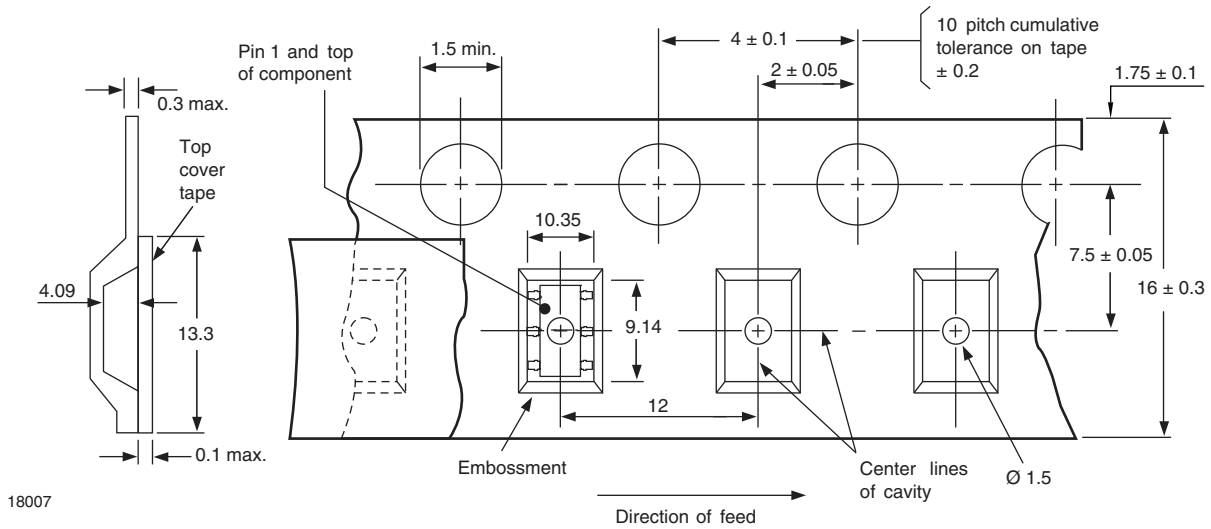


Fig. 15 - Tape and Reel Shipping Medium (1000 pieces on reel)

SOLDER PROFILES

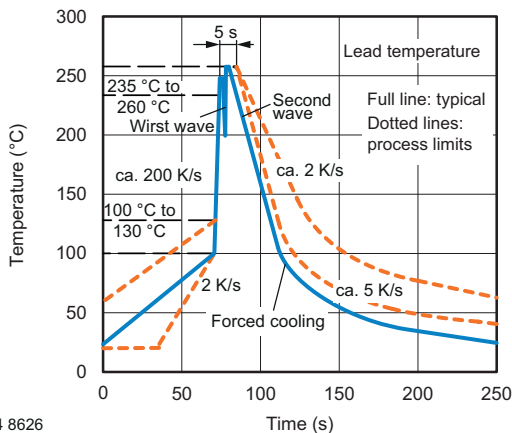


Fig. 16 - Wave Soldering Double Wave Profile According to J-STD-020 for DIP Devices

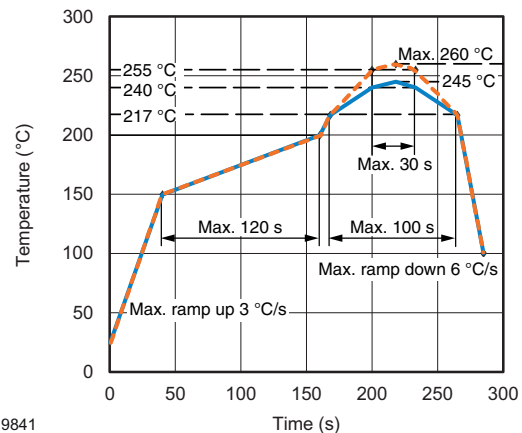


Fig. 17 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020 for SMD Devices

HANDLING AND STORAGE CONDITIONS

ESD level: HBM class 2

Floor life: unlimited

Conditions: $T_{amb} < 30\text{ °C}$, $RH < 85\%$

Moisture sensitivity level 1, according to J-STD-020



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